

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	40350	interconnect\$3 with (solder near3 mask epoxy near3 resin bismaleimide adj triazine dielectric insulat\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 07:25
L2	13488	(thermal near4 expansion) with (solder near3 mask epoxy near3 resin bismaleimide adj triazine dielectric insulat\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 07:24
L3	240	interconnect\$3 with ((thermal near4 expansion) with (solder near3 mask epoxy near3 resin bismaleimide adj triazine dielectric insulat\$3))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 07:28
L4	205	3 and coefficient	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 07:25
L5	159	4 and interconnect\$3 with (opening hole via groove trench)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 07:27
L6	22	5 and interconnect\$3 with mask\$3	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 07:27
L7	22	6 and (interconnect\$3 thermal expansion solder mask epoxy resin bismaleimide adj triazine dielectric insulat\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 07:28
L8	159	5 and (interconnect\$3 thermal expansion solder mask epoxy resin bismaleimide adj triazine dielectric insulat\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 07:30
L10	13	8 and (dielectric near5 mask\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 07:32

L11	59	8 and (expansion with ("same" similar equal\$3))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 08:15
L12	5	11 and solder adj mask	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 09:20
L13	41	(interconnect\$3 with dielectric) with solder adj mask	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 09:21
L14	0	13 and glas adj transition	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 09:21
L15	6	13 and glass adj transition	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/09 09:21
S2	1	10/604650	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/05 13:05
S3	0	((solder near4 mask\$3) (mask\$3 with (epoxy near3 resin 'bt' bismale\$10))) with dielctric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:38
S4	0	(solder near4 mask\$3) with dielctric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:10
S5	659	(solder near4 mask\$3) with packag\$3	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:11
S6	0	S5 and ((solder near4 mask\$3) with dielctric)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:11
S7	150	S5 and ((solder near4 mask\$3) with (epoxy resin 'bt' bismaleimide adj triazine))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:13

S9	19	S7 and ((dielectric) with (epoxy resin 'bt' bismaleimide adj triazine))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:22
S10	5	S9 and ((dielectric mask\$) with (thermal\$5 coefficient\$3 expansion\$4))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:16
S11	11	S9 and (temperature degree)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:23
S12	166	(solder near4 mask\$3) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:04
S13	3421	(dielectric) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:06
S14	15927	(dielectric insulat\$3) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:39
S15	662	(solder near4 mask\$3) with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:03
S16	13	((solder near4 mask\$3) with dielectric) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:57
S17	3421	S13 and S13	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:59
S18	240	S17 and (solder with (expansion\$4 coefficient thermal\$3))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:00
S19	19	S12 and S13	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:59

S20	119	S18 and (dielectric with (expans\$4 coefficient thermal\$3))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:23
S21	101	S20 and packag\$3	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:00
S22	618	(solder adj mask\$3) with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:07
S23	25	S22 and (solder) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:05
S26	18	S23 and (dielectric) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:06
S27	701	(solder adj mask\$3 soldermask\$3) with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:13
S28	158	S27 and (solder adj mask\$3 soldermask\$3) with (epoxy resin 'bt' bismaleimide adj triazine)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:08
S29	131	S28 and (epoxy resin 'bt' bismaleimide adj triazine) with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:11
S30	131	S29 and (epoxy resin 'bt' bismaleimide adj triazine dielectric solder adj mask\$3 soldermask\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 14:36
S31	38	S30 and (expans\$4 coefficient thermal\$3) with (solder adj mask\$3 soldermask\$3 dielectric)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 09:49
S32	0	10/8108049	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 09:50

S33	1	10/808049	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 09:56
S34	0	10/698258	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 09:56
S35	701	S27 and (dielectric expans\$4 coefficient thermal\$3 soldermask solder dj mask)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:25
S36	701	S35 and (dielectric with (expans\$4 coefficient thermal\$3 soldermask solder dj mask))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:25
S37	701	S35 and ((dielectric expans\$4 coefficient thermal\$3) with (soldermask solder dj mask))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:26
S38	701	S36 and ((dielectric expans\$4 coefficient thermal\$3) with (soldermask solder dj mask))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:26
S39	701	S38 and ((dielectric expans\$4 coefficient thermal\$3 soldermask solder dj mask))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:27
S40	174	S38 and (expans\$4 near4 coefficient).	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:27
S41	6	"5665526"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 14:30
S42	2	10/688354	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 14:36
S43	1	10/808049	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 16:59

S45	4820	interconnect\$3 and ((solder near mask epoxy bismaleimide adj triazine) near5 (dielectric insulat\$3))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/05 13:10
S46	78	S45 and (epoxy bismaleimide adj triazine) near5 (mask\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/05 13:10
S47	27	S46 and ((solder near mask epoxy bismaleimide adj triazine dielectric insulat\$3) with thermal)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/05 13:28
S49	15	S47 and ((solder near mask epoxy bismaleimide adj triazine dielectric insulat\$3) with expansion)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/05 13:12
S50	13	S49 and ((solder near mask epoxy bismaleimide adj triazine dielectric insulat\$3) with coefficient)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/05 13:12
S51	2	S50 and ((equal\$3 'same') with thermal)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/05 13:19
S52	7	S50 and ((equal\$3 'same' similar) with thermal)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/05 13:21
S53	2	S52 and mask\$4 near5 dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/05/05 13:22